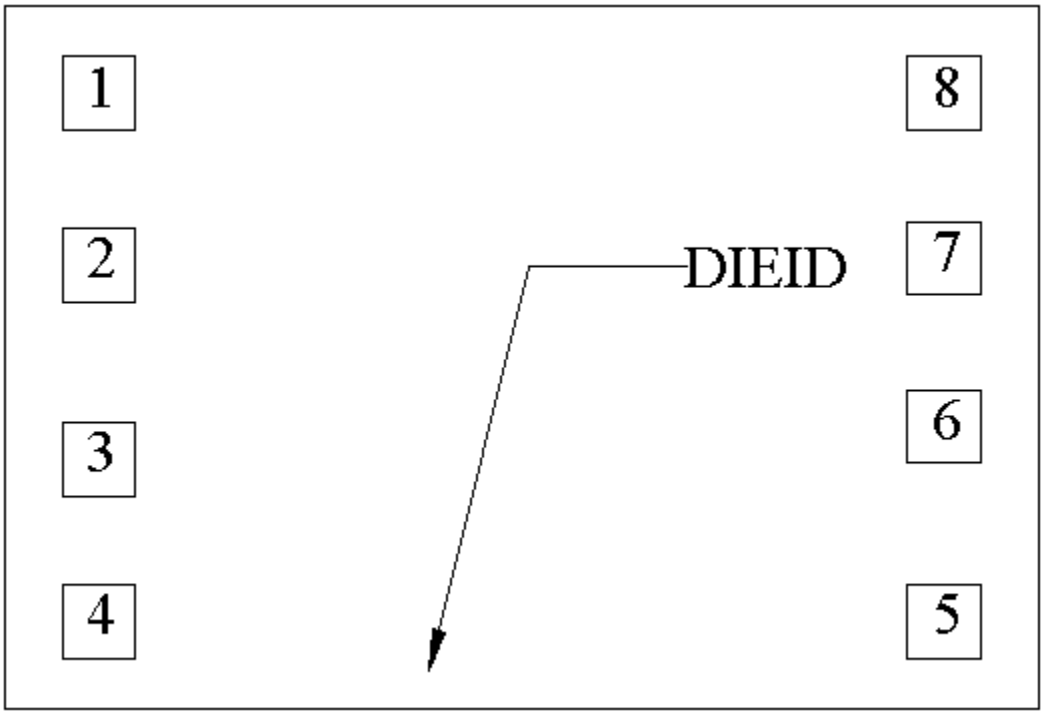
LMH6622 MDC MWC
DUAL WIDEBAND, LOW NOISE, 160MHZ, OPERATIONAL AMPLIFIERS

January 09,2003

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMH6622A	Bond Pad Opening Size (min)	90µm x 90µm
Die Step	A	Bond Pad Metalization	0.5%COPPER_BAL. ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1270µm x 879µm 50.0mils x 34.6mils	Back Side Connection	Floating
Thickness	216µm Nominal		
Min Pitch	198µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES X	Y	PAD SIZE X		Y
OUTPUT A	1	-519	324	90	x	90
INPUT A -	2	-519	113	90	x	90
INPUT A+	3	-519	-125	90	x	90
V -	4	-519	-324	90	x	90
INPUT B+	5	519	-324	90	x	90
INPUT B -	6	519	-85	90	x	90
OUTPUT B	7	519	121	90	x	90
V+	8	519	324	90	x	90

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